Melissa's Opening Letter

Happy 2018 FlexTech community! We had a busy year in 2017 beginning with the 5 world-wide FLEX events attracting more than 1200 participants. At these events, we focused on relevant technological advancements, explored supply chain opportunities, and began the formation of a global team of thought leaders in the world of flexible hybrid electronics (FHE). Last year, we saw advancements in flexible power sources, printing, integration of ultra-thin high performance silicon, flexible displays and gesture control, and flexible biosensors, just to name a few. SEMI-FlexTech working with you, our members, will maintain the momentum established in 2017 by broadening our outreach to all segments of the global supply chain for a healthy and profitable FHE community.

FlexTech's Info Hub

This year, we can look forward to the development of an information hub where you will be able to find, at your fingertips, news, project summaries, consortia publications, technical data, and much more content in a members-only portal.

Our R&D efforts will also continue with at least one request-for-proposal this year and, as in prior years, we will work closely with our AFRL and ARL government partners to fund and manage relevant technology development programs to advance the state-of-the art and fill ecosystem gaps. In addition, we will be kicking off a concerted FHE standards effort building upon the industry-critical standards SEMI has been developing for many years. With the collective industry intelligence of our membership, and your continued participation in shaping the flexible electronics market and supply chain, we are looking forward to a productive year.

2018FLEX & MEMS and Sensors Technical Congress

2018FLEX is rapidly approaching and we hope to see you in Monterey for this pinnacle event. The FLEX conference has grown into arguably the premier assembly of industry-leading technologists in the flexible electronics industry. This year will be the first co-location with MEMS & Sensors Technical Congress, organized by the MEMS & Sensors Industry Group (MSIG). MSIG presents one of our newest SEMI strategic alliances and the Technical Congress will feature the latest technological advancements in the field of sensors and transducers.

The 2018FLEX agenda is an exciting one including short courses, a business strategy session, workforce development and diversity topics, as well as the technical depth and breadth FLEX is known to provide. Keynotes from Thin Film Electronics, Draper Labs, Luminit, NASA, Panasonic and Cortera open the event on February 13th so if you have not registered, visit us at 2018FLEX.com now to be part of this 2018 opening event and the FHE leadership community.
One last highlight I would like to bring to your attention is a technology benchmarking effort SEMI-FlexTech and ARL are sponsoring with a team from Cal Poly driving the project. The principal investigators and students from Cal Poly will be at 2018FLEX in Monterey interviewing leading companies and organizations. FlexTech governing and technical council members will receive the results of this study as a benefit of their continued contribution and membership. Contributing organizations that are not FlexTech members will receive an executive summary of the completed study for their participation. If you wish to participate, be sure to scroll down to the Cal Poly section of the newsletter for additional information regarding the Cal Poly work and how to get involved.

Melissa Grupen-Shemansky
CTO

Project Updates

PROJECT CLOSE OUT - 17-16 Microfluidic Systems Packaging (Human Performance Monitoring & Sensor Systems) - University of Arizona

FlexTech Members Only Content
Cal Poly San Luis Obispo is conducting a benchmark study over the course of 9 months to identify and interview current companies and research groups involved in flexible and printed electronics. Data compiled from the research on the processing technologies and performance targets for functional components will serve as a 3-year, 5-year and 10-year horizon for benchmarking.

A free executive summary of the benchmark is provided to the participants and the completed report will be available for purchase at a later time.

The Cal Poly project team will be at the 2018FLEX Conference in Monterey, CA from February 12-15, 2018 to meet up with any interested companies and organizations there. Interested in contributing to this benchmark study? Please fill out this survey or call (805) 756-2540 for more information and read more in the link below for corresponding areas of interest.

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News and Announcements

CES - The Show Must Go On!

The 2018 Consumers Electronics Show was one of the LARGEST and HOTTEST technology shows to kick off 2018. Even with a raging storm threatening to flood the Sands Expo and an unexpected power outage at the Las Vegas Convention Center, it was a jam packed week filled with non-stop excitement on the show floor.

SEMI and 6 member exhibitors were there at our pavilion to provide our members a new form of customer outreach as well as establish ourselves as the leading organization for the global electronics manufacturing supply chain. We met many potential partners, closed some deals and gave our share of interviews.

Looking ahead to 2019, SEMI will be expanding our booth space to accommodate even more of our members on the floor and fully showcase the reach of our community across the supply chain.
Upcoming Events

2018FLEX
Monterey, California, USA
FEBRUARY 12-15, 2018

Smart Transportation @ WCX: SAE World Congress Experience
Detroit, Michigan, USA
APRIL 10-12, 2018

Exhibit Now

2018FLEX Japan
Shinagawa, Tokyo, Japan
APRIL 19-20, 2018